



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ERU chokes

ERU 19, helically wound

Series/Type: **B82559*A019**

Date: June 2016

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SMD

Rated inductance 1.0 30 μ H
Saturation current 10.1 ... 43 A



Construction

- High temperature ferrite core
- Magnetically shielded
- Helical winding
- Self-leaded construction
- Under body termination
- 3 pins for improved reliability

Features

- High rated current
- Extremely low DC resistance
- Very low profile and extremely small footprint
- Suitable for pick-and-place processes
- RoHS-compatible
- Easily customized
- AEC-Q200 qualified

Applications

Energy storage chokes for

- DC-DC converters
- VRM modules
- POL converters
- Solar converters

Terminals

Lead-free tinned

Marking

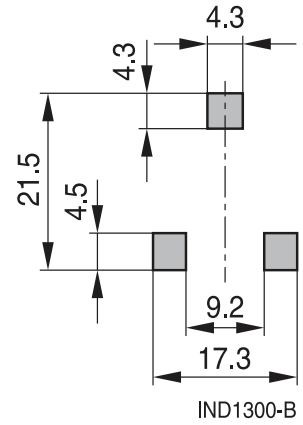
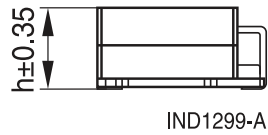
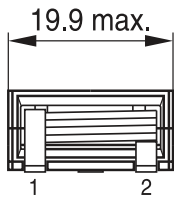
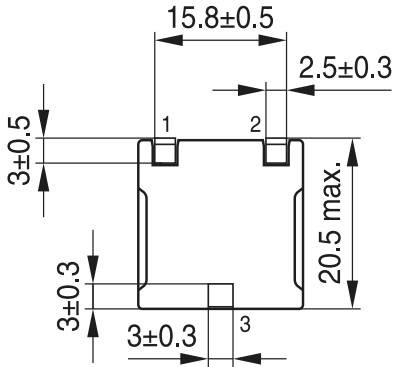
Manufacturer, ordering code, date of manufacture and production place (YYWWD/X),

Delivery mode and packing units

- Blister tape

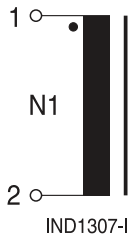
SMD

Dimensional drawing and layout recommendation



Dimensions in mm

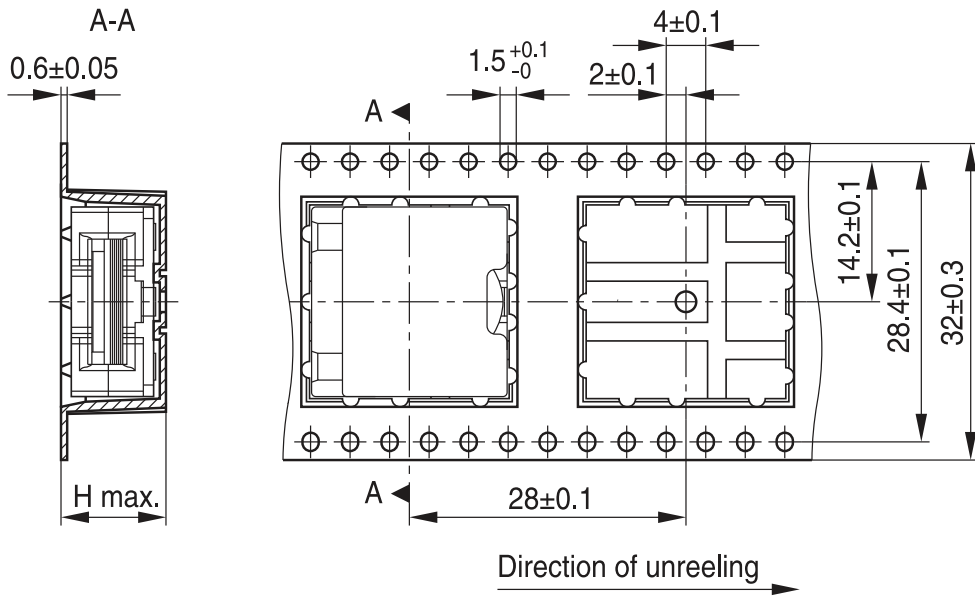
Circuit diagram



SMD

Taping and packing

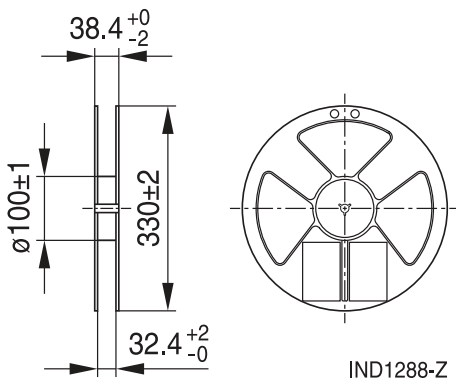
Tape:



IND1301-C-E

Dimensions in mm

Reel:



IND1288-Z

Dimensions in mm

Height (mm)		Packing unit per reel
component h	cavity H	
8.35	10.2	240
9.15	11.0	200
9.75	11.6	190
10.85	12.7	160

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Technical data and measuring conditions

Rated inductance L_R	Measured at 100 kHz, 0.1 V, +25 °C
Inductance tolerance	±10%
Saturation current I_{Sat}	Current that will result in an approximately 20% drop in the inductance values at the specified temperature
DC resistance R_{DC}	Measured at +25 °C
Self-resonant frequency	> 2 MHz
High voltage: N1 - core	200 V DC, 1 s
Solderability (test of wettability of the pins)	(245 ±5) °C, (3 ±0.3) s, wetting of soldering area ≥95% (based on IEC 60068-2-58, solder bath method)
Resistance to soldering heat	To JEDEC J-STD 020D (Tc: +245 °C on pin)
Operating temperature	-40 °C ... +150 °C (component)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH

Characteristics and ordering codes

L_R	$I_{sat, 25°C}$	$I_{sat, 100°C}$	R_{DC} (max)	R_{DC} (typ)	Height h (nom.)	Approx. weight	Ordering code
μH	A	A	mΩ	mΩ	mm	g	
1.0	43.0	37.5	1.20	0.95	8.35	9.8	B82559A2102A019
1.5	42.5	36.3	1.70	1.45	9.15	10.3	B82559A3152A019
2.2	37.8	32.2	2.20	1.80	9.75	11.1	B82559A4222A019
3.3	31.5	27.0	2.70	2.30	10.85	12.7	B82559A5332A019
4.7	23.0	20.2	2.70	2.30	10.85	12.7	B82559A5472A019
6.8	18.6	16.4	8.25	7.70	8.35	9.3	B82559A6682A019
10.0	14.4	12.7	9.55	8.90	8.35	9.6	B82559A7103A019
15.0	13.0	11.4	12.15	11.35	9.15	10.7	B82559A9153A019
20.0	12.0	10.6	14.75	13.75	9.75	11.8	B82559A0203A019
30.0	10.1	8.7	18.65	17.35	10.85	13.0	B82559A0303A019

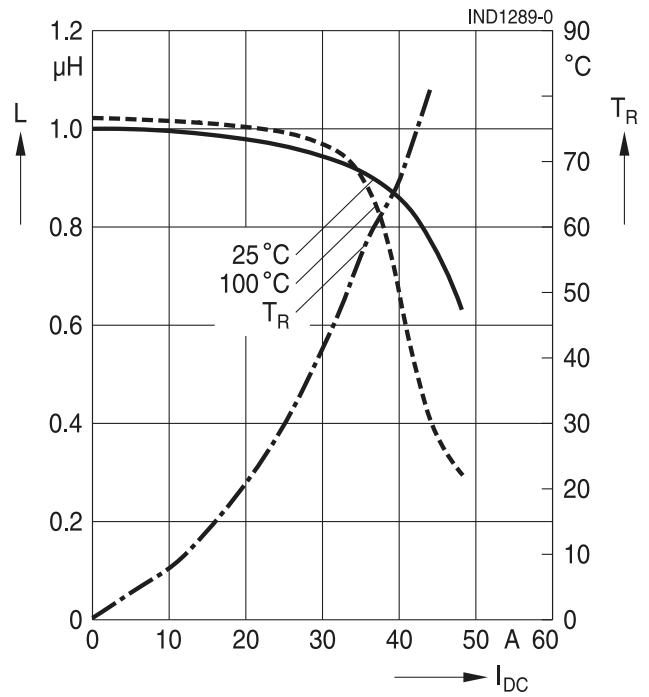
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Inductance L versus DC load current I_{DC}

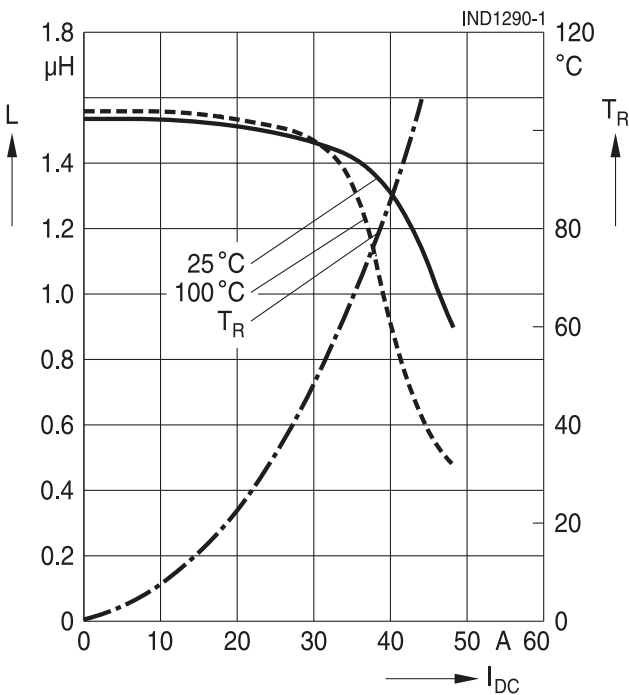
The temperature rise ΔT is measured at an ambient temperature of +25 °C. A current is applied for 30 minutes and the temperature is measured via a thermocouple placed on top of the device. No forced air cooling is applied.

The inductance vs current curves are generated by measuring the inductors at +25 °C and +100 °C.

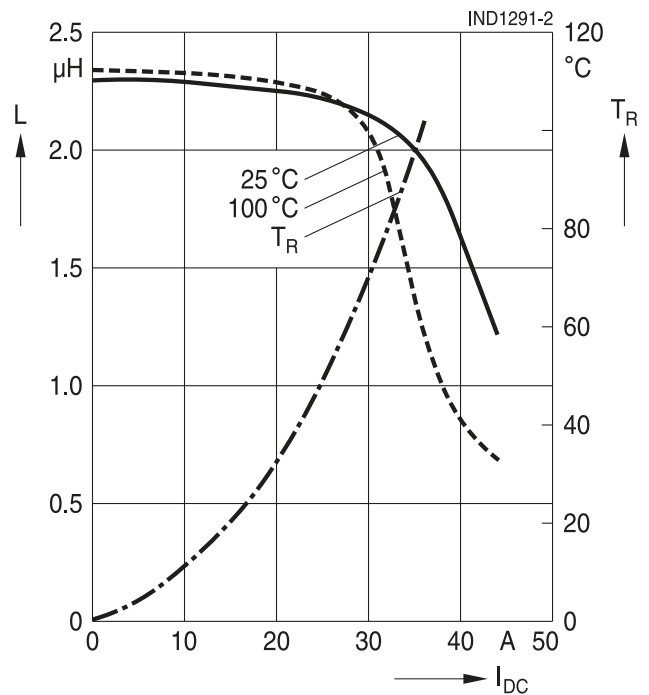
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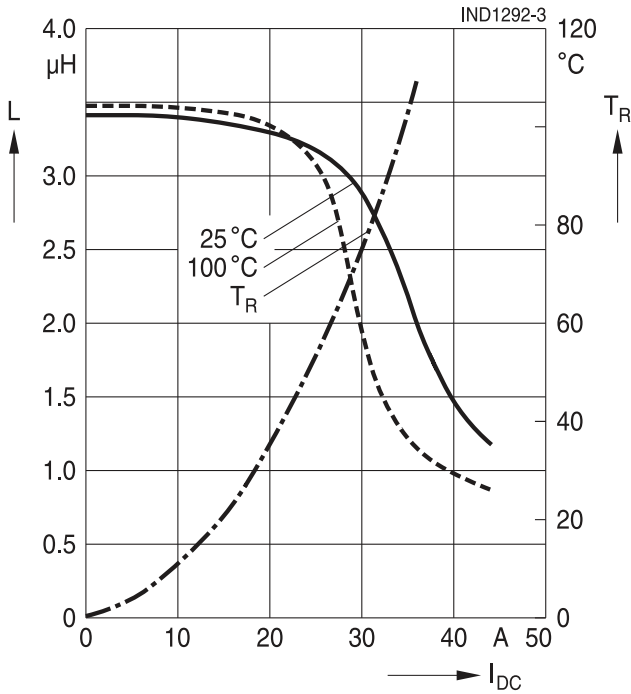


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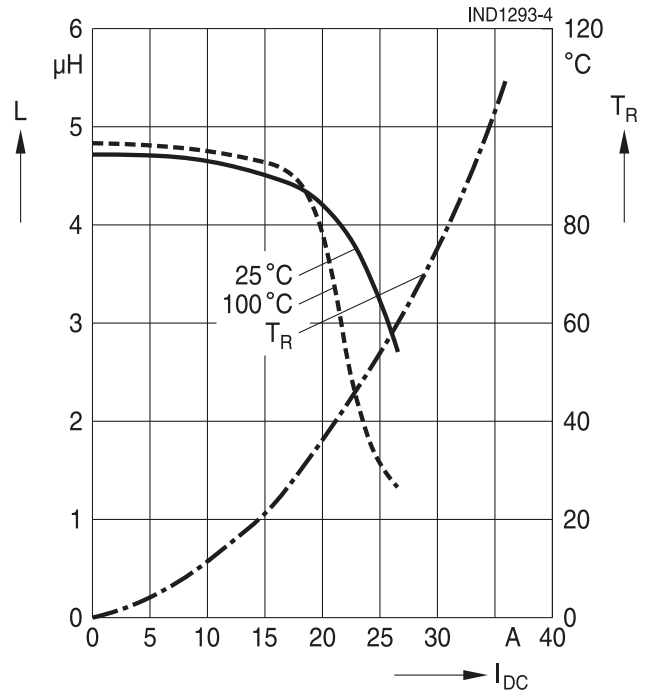


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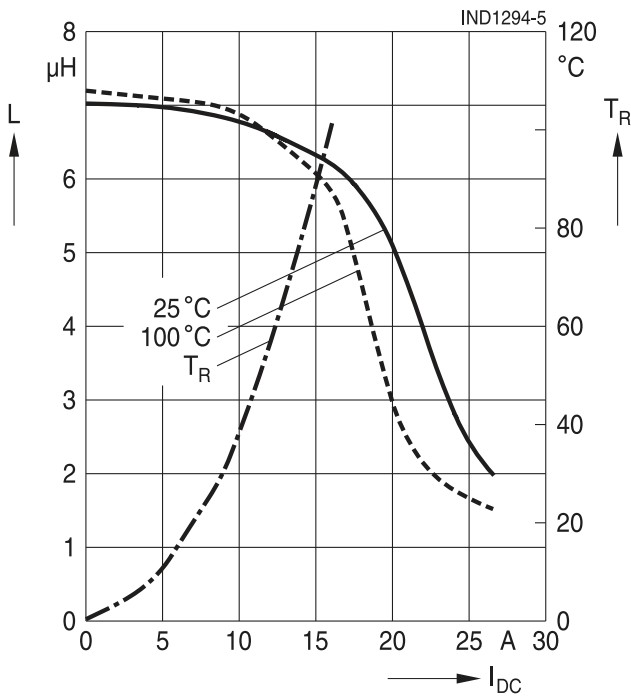
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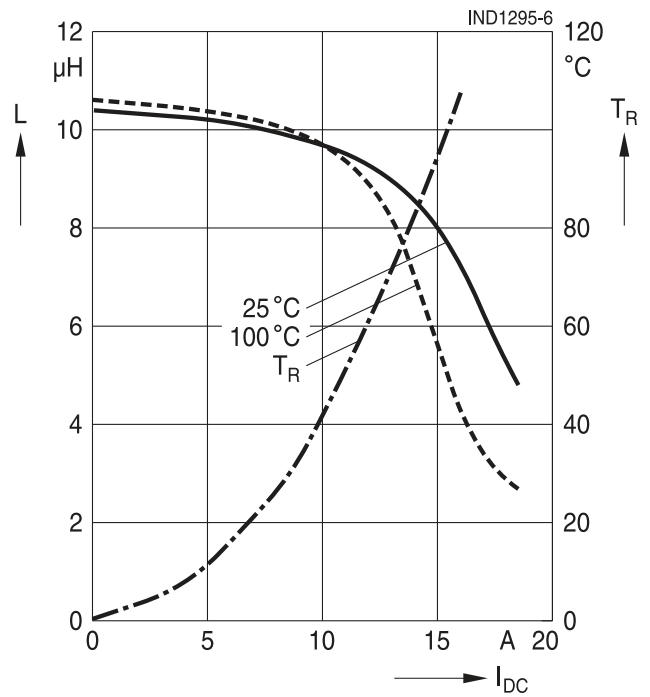
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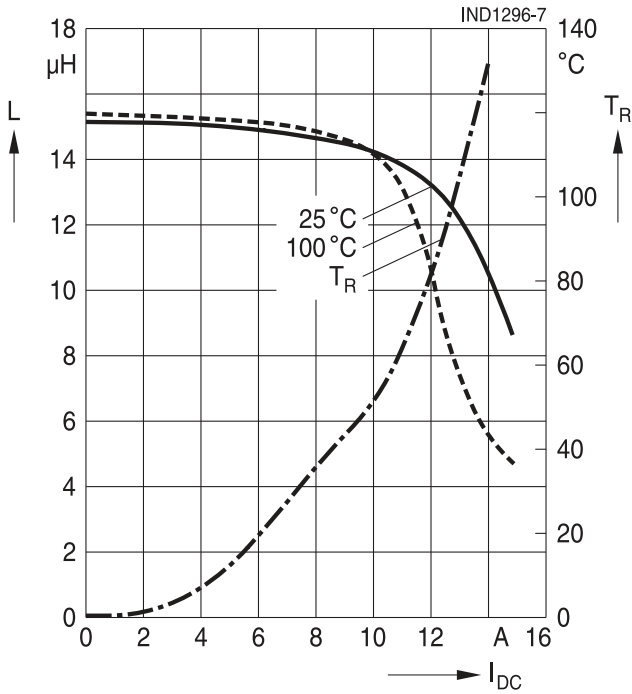
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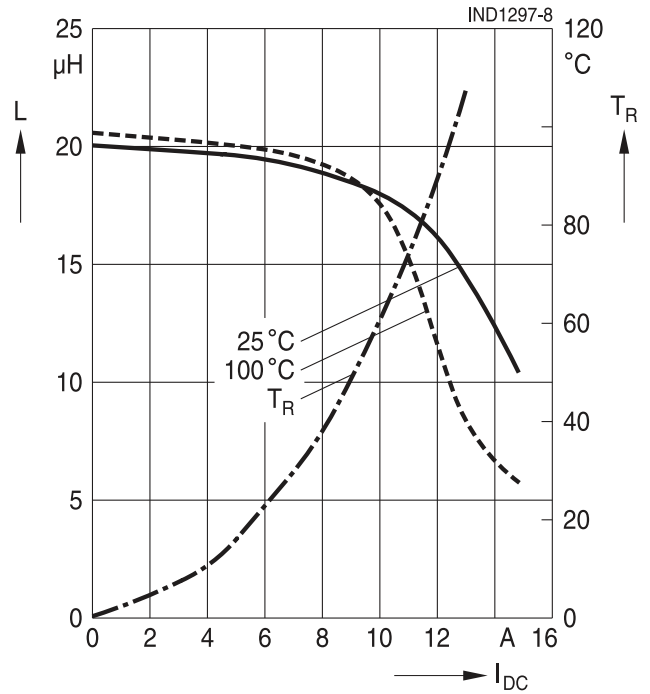
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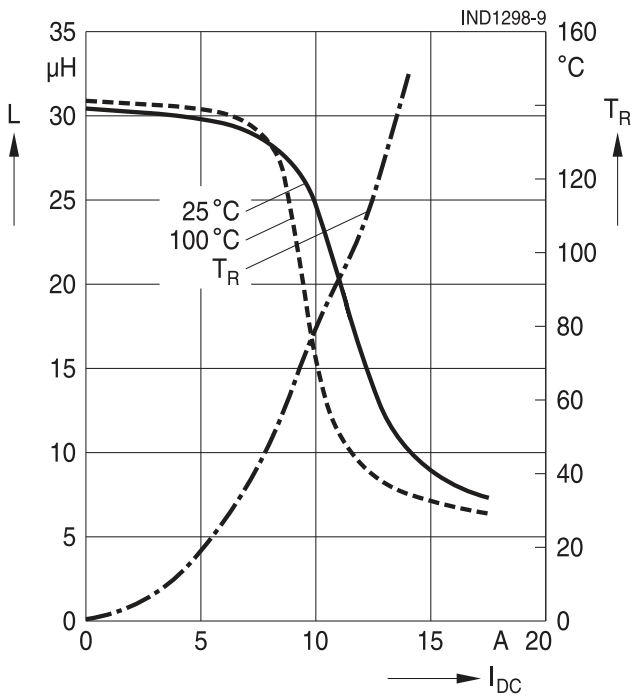
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B82559A0203A019



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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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